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**(54) Title (EN):** EPOXY RESIN COMPOSITION

**(54) Title (FR):** COMPOSITION DE RÉSINE ÉPOXYDE

**(54) Title (JA):** エポキシ樹脂組成物

**(57) Abstract:**

**(EN):** Provided is an epoxy resin composition capable of achieving excellent low dielectric properties and high adhesion to metal. Specifically, an epoxy resin composition is provided that contains organic particles and an epoxy resin having a specific structure.

**(FR):** L'invention concerne une composition de résine époxyde permettant d'obtenir d'excellentes propriétés diélectriques faibles et une forte adhérence au métal. L'invention concerne en particulier une composition de résine époxyde qui contient des particules organiques et une résine époxyde ayant une structure spécifique.

**(JA):** 優れた低誘電特性及び金属への高い接着強度が達成できるエポキシ樹脂組成物が提供される。具体的には、特定の構造を有するエポキシ樹脂、及び有機微粒子を含有する、エポキシ樹脂組成物が提供される。

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